



# Indigo Xtreme™ Installation Guide for Skylake-X™ & Broadwell-E™ Processors

This product is intended for installation only by expert users. Please consult with a qualified technician for installation. Improper installation may result in damage to your equipment. Enerdyne Solutions assumes no liability whatsoever, expressed or implied, for the use of these products, nor their installation. The following instructions are subject to change without notice. Please visit our web site at [www.indigo-xtreme.com](http://www.indigo-xtreme.com) for updates.

## STEP 1: QUICK OVERVIEW:

### STEP 1.1: Indigo Xtreme:

Engineered Thermal Interface for Skylake-X (Socket 2066) & Broadwell-E (Socket 2011-3)

Indigo Xtreme™ is an Engineered Thermal Interface (ETI) that fits neatly between a CPU lid and water block or heat sink to keep CPUs cooler. Unlike greases, metallic thermal interface pads or liquid metal alloys, Indigo Xtreme is a self-contained and sealed structure, deploying a Phase Change Metallic Alloy (PCMA) which reflows and fills surface defects on the CPU lid and water block/cooler. The resultant interfacial layer is void-free and robust, with low thermal contact and bulk resistance.



Important: Unlike most thermal interface products, the Indigo Xtreme form-factor is optimized for each application.



Attempting to use Indigo Xtreme with CPUs or heat sinks other than those specified may result in degraded performance or interfacial failure (See: Supported Hardware).

### STEP 1.2: Compatibility List:

#### Supported Hardware:

Supported CPUs: Intel Skylake-X & Broadwell-E Core™ i7/i9 processors

#### Supported Water block/Cooler Types:

In general, water blocks/coolers that contact entire surface of CPU lid are compatible with Indigo Xtreme.

#### Unsupported Cooler Types:

Cooler surfaces that do not contact entire CPU lid surface, contain heat pipe channels on the mounting base, or AIO coolers with exposed bolts contacting the CPU lid are incompatible with Indigo Xtreme.



**Prior to installation, see the Cooler Compatibility Application Note found on the Documentation page at: [indigo-xtreme.com](http://indigo-xtreme.com).**



### STEP 1.3: ETI Kit Contents:

The Indigo Xtreme ETI is offered as part of an Engineered Thermal Interface Kit. This kit includes several cleanroom-grade surface cleaning products for (2) complete installations.

The ETI kit includes:

- Indigo Xtreme ETIs (2 installations)
- Cleanroom-grade dry wiper cloths
- Cotton cleaning swabs
- Indigo Xtreme Clean™ (sample size)
- Pair of powder-free nitrile gloves
- Detailed Installation Guide



Check the condition of the ETI kit before installation.

## STEP 2: INSTALLATION PROCEDURE:

### STEP 2.1: Pre-Installation Notes:



Read entire instructions before beginning installation. **For large air coolers:** Computer operating system and temperature monitoring utilities (such as SpeedFan™ and Prime95™) must be installed prior to use; clock frequency and voltage must be set back to default. Do Not Disable the Thermal Control feature that protects your CPU from overheating.



See the applicable Application Note (on the Indigo Xtreme website) with installation tips and recommendations for your specific water block or cooler. Contact Enerdyne Support if you have any questions.

### STEP 2.2: Thermal Interface Compound (grease/paste) Removal:

Using a supplied dry wiper cloth, apply pressure to thoroughly remove any existing interface grease from the CPU lid and water block/cooler. Clean with fresh areas of the wiper cloth until no visible grease residue is detected on the wiper.



If removing metal pad or liquid metal TIM residue, refer to manufacturer's specific cleaning methods.

### STEP 2.3: Put on Gloves:

Prior to the final degreasing step, the supplied powder-free nitrile gloves should be worn to prevent any finger oils or contaminants from contacting the CPU lid, water block/cooler, and ETI surfaces and to prevent skin contact with Indigo Xtreme Clean™.



Stray grease compound can be mitigated as gloves are applied immediately following the Thermal Interface Compound Removal step.

#### STEP 2.4: Degrease CPU lid and Water Block/Cooler Surfaces:

Saturate a dry wiper cloth with Indigo Xtreme Clean™; use ~1/2 trial size bottle per ETI installation; thoroughly wipe the CPU lid; repeat with the water block/cooler interfacial surfaces. Continue to wipe each surface with fresh areas of the wiper until no visible residue is detected on the wiper. Wipe all surfaces of any visible lint, fibers, or particulates.

Install the CPU into the motherboard socket. Refer to motherboard or CPU installation instructions. The ETI can only be applied after correct installation of the CPU.



Be prepared to wipe the CPU lid and water block/cooler surfaces immediately upon saturating each dry wiper cloth as the Xtreme Clean™ solvent will quickly evaporate. When finished, seal the used wiper in the ETI kit clear bag. New CPUs or coolers must be degreased as well. Use only the supplied Indigo Xtreme Clean™ for the degreasing step.



Use the Xtreme Clean™ solvent in a well-ventilated area. Avoid contact with plastics (such as keyboards, computer cases, cooling fans, some water block housings, coolant tube fittings, cables, etc.). Also, avoid contact with coolant tubing, gaskets, etc.

#### STEP 2.5: Indigo Xtreme Handling:

The Indigo Xtreme ETI may be handled on the blue surfaces only within a lint-free environment.



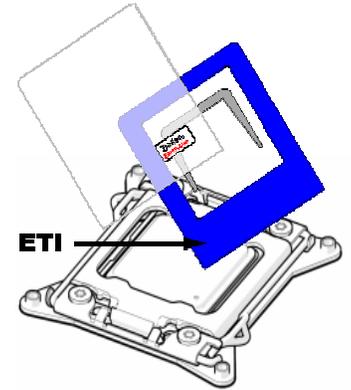
Do not remove the clear Top and Bottom liners prior to the specific installation step. Do not bend, flex or puncture any portion of the ETI. Keep all chemical agents (Indigo Xtreme Clean™, etc.) away from the ETI.

#### STEP 2.6: Bottom Side Liner Removal:

Remove the "Bottom" side rectangular clear liner by slowly peeling the liner, beginning from the corner with the white BOTTOM" label. Hold the ETI on the blue edges (to prevent any wrinkling or warping). **Do not** remove the "Top" liner at this step.



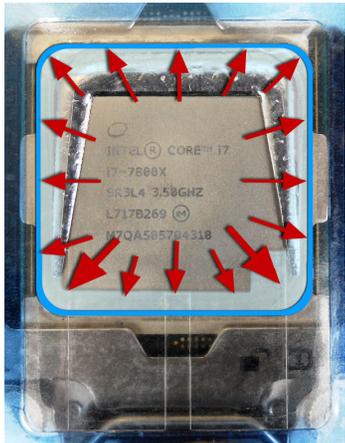
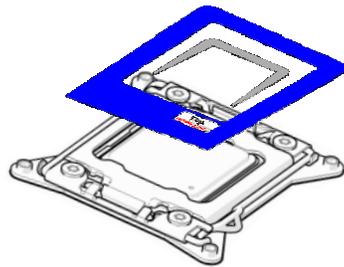
Do not touch the exposed adhesive area after removal of the clear liner. Once the liner has been removed, proceed immediately to Step 2.7: Alignment and Placement.



#### STEP 2.7: Alignment and Placement:



Orientation and alignment of the ETI to the CPU lid and socket is critical. Orient the ETI such that the "Bottom" side is facing the CPU lid.



Hold the ETI on the blue edges (with both hands). Ensure that the ETI is oriented with CPU lid/socket as shown. Center the narrow, blue alignment ring to the CPU lid top surface before making contact. Carefully lower the ETI onto the CPU lid surface. With moderate, downward finger pressure, completely press down all ETI surfaces onto the CPU lid by following the blue alignment ring (small red arrows). Additionally, thoroughly press down the area surrounding the vent hole (Broadwell-E) and adhesive region to the CPU lid (large red arrows).



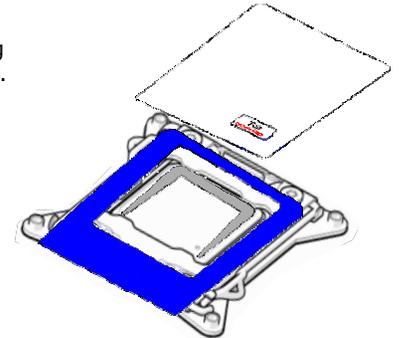
It is critical that the narrow blue alignment ring is completely on the CPU lid and all blue ring surfaces are thoroughly pressed down.

#### STEP 2.8: Top Side Liner Removal:

Remove the "Top" side rectangular clear liner by slowly peeling the liner, beginning from the corner with the white "TOP" label.



Do not touch any of the clear surfaces after removal of the clear liner. Once the liner has been removed, proceed immediately to Step 2.9: Heat Sink/Block Mounting.



#### STEP 2.9: Water Block/Cooler Mounting:



It is imperative that the water block/cooler is aligned correctly before it makes contact with the ETI. **Some AIO coolers may require a specific orientation to avoid exposed bolts from contacting the CPU lid.** For circular AOI coolers, the corners of the CPU lid (seen as gray square) should be positioned between each bolt.



Apply a uniform torque to all thumb nuts/screws (by alternating the tightening of the nuts). Turn all thumb nuts until fully bottomed or to your cooler's recommended torque.



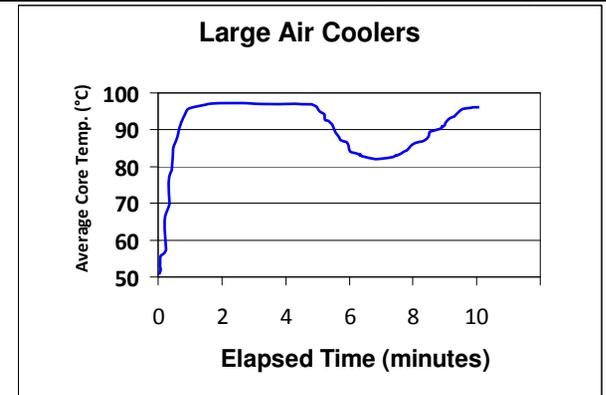
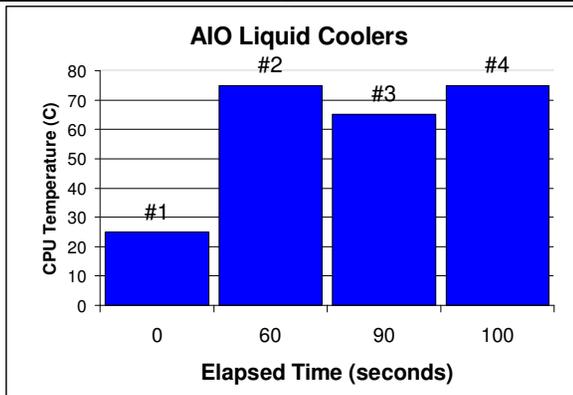
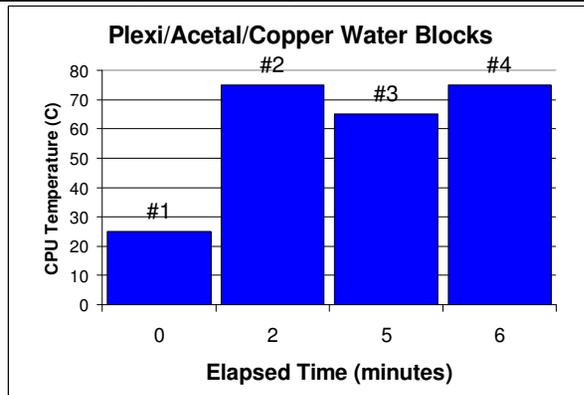
## STEP 3: ETI REFLOW PROCEDURE:

Follow the reflow steps below for your water block or cooler type; the motherboard must be in a horizontal position for proper reflow.



As part of installation, the Indigo Xtreme ETI must first be heated with the CPU running under load in order to reflow (melt) the PCMA alloy. Failure to perform the exact reflow procedure may result in unacceptable thermal performance. Video demonstrations of ETI reflow can be found on the Indigo Xtreme website at: <http://www.indigo-xtreme.com>

Step	Plexi/Acetal/Copper Water Blocks	AIO Liquid Coolers	Large Air Coolers
3.1	Connect up any water block liquid lines and unplug pump.	Unplug AIO liquid cooler pump.	See the "Indigo XS/Xtreme Application Note for Noctua NH-D14 CPU Coolers" for large air cooler reflow instructions.
3.2	Boot the computer directly into BIOS (DEL/ESC/F2/F12 Key).	Boot the computer directly into BIOS (DEL/ESC/F2/F12 Key).	Be certain there is no airflow within the PC (case fans, etc); it is recommended to close up the PC case reflow complete.
3.3	Once in BIOS, locate the CPU temperature (as a single temperature point) and note the initial reading.	Once in BIOS, locate the CPU temperature (as a single temperature point) and note the initial reading.	Boot the computer into Windows (stock freq. and voltage).
3.4	As seen in the bar graph below, CPU temperature will steadily rise from room temperature (bar #1) to a peak temperature of ~65-75°C (bar #2); note this peak temperature.	As seen in the bar graph below, CPU temperature will steadily rise from room temperature (bar #1) to a peak temperature of ~65-75°C (bar #2); note this peak temperature.	Open SpeedFan™, select the "Charts" tab, and check all core boxes to track the core temperatures during reflow.
3.5	The peak temperature may remain stable for a few minutes. Following the peak, CPU temperature will slowly dip ~3-6°C (bar #3). The dip will indicate the start of reflow.	Typically within seconds of the peak, CPU temperature will slowly dip ~3-6°C (bar #3). The temperature dip will indicate the start of reflow.	Open Prime 95™ or equivalent burn program and run a "Torture Test" for all available threads.
3.6	The elapsed time from Boot-to-temperature dip may be approx. 4-7 minutes (all-copper blocks typically require more time than plexi/acetal blocks).	The elapsed time from Boot-to-temperature dip may be approx. 1-2 minutes for AIO liquid coolers.	Follow the average core temperature profile (with SpeedFan™ in chart mode) illustrated in the chart below.
3.7	The CPU temperature will dip to a bottom temperature point and then slowly rise again. Reflow is now complete.	The CPU temperature will dip to a bottom temperature point and then slowly rise again. Reflow is now complete.	The Temperature Dip will indicate reflow. Large air coolers may require several minutes for reflow.
3.8	Following the bottom temperature point and rise (bar #4), shut down the PC. <b>Do not</b> turn on the pump or fans.	Following the bottom temperature point and rise (bar #4), shut down the PC. <b>Do not</b> turn on the pump or fans.	Following the Temperature Dip and rise back to ~90°C, shut down PC. <b>Do not</b> turn on the fans.
3.9	Allow PC and water block to cool for at least 60 minutes before booting and connecting fans/water pumps.	Allow PC and liquid cooler to cool for at least 60 minutes before booting and connecting fans/water pumps.	Remove cloth shroud and open PC case. Allow air cooler to cool for at least 60 min. before booting and connecting fans.



Intel multi-core CPUs have built-in protection (Adaptive Thermal Monitor) that prevents the CPU from exceeding maximum core temperatures, thereby preventing damage to the CPU.



Avoid any bumping or excessive pressure on the water block/cooler and keep the computer in the horizontal position while cooling down. If the average core temperature does not follow a similar temperature profile as seen in the previous graphics, then improper reflow may have occurred. Proceed to "Removal" and re-install a new ETI.

## **STEP 4: REMOVAL OF INDIGO XTREME:**

To disassemble, release the clamping force from the water block/cooler. The ETI may then be removed (intact) by first slowly peeling each corner. The ETI is designed to adhesively capture excess alloy (from differences of CPU lid/heat sink interfacial roughness and planarity) on their surfaces. Any residual adhesive on the CPU or heat sink/water block may be removed with Xtreme Clean, acetone, or xylene and a clean wiper or cotton cleaning swab. Residual alloy is best removed by wetting a swab with Xtreme Clean and rotating the swab to loosen and collect the alloy particles. The edge of a plastic credit card may also be used to remove any adherent alloy.



Indigo Xtreme is a single-use interface product and any removal of the heat sink (pre/post-reflow) will require a new ETI. All interface material and adhesive residue must be removed and the CPU and heat sink re-cleaned (with the surface cleaning supplies included in the ETI kit only) prior to the re-installation of a new ETI.

## **REFERENCES:**

**Burn-in/Torture Testing Program:** Prime95™: <http://www.mersenne.org/freesoft>

**Temperature monitor:** Although, numerous temperature monitoring programs exist, SpeedFan™ provides the real-time charting/graphing mode necessary for reflow: <http://www.almico.com/speedfan.php>

The Material Safety Data Sheet (MSDS) for Indigo Xtreme Clean™ can be found at: <http://www.indigo-xtreme/documentation>

Contact us for more information about this or other Indigo Xtreme applications at: [info@enerdynesolutions.com](mailto:info@enerdynesolutions.com)

Store Indigo Xtreme at room temperature conditions of 22°C (72°F) and 50% R.H., preferably in the original sealed enclosure and plastic bag.

## **DISCLAIMER:**

Enerdyne Solutions is not responsible for any damages due to external causes, including but not limited to, improper use, accident, neglect, alteration, repair, improper installation, improper testing, or damages caused by overclocking.

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